Special Issue

Design, Fabrication, Testing of MEMS/NEMS

Message from the Guest Editors

Here, we would like to introduce the special issue of "Design, Fabrication, Testing of MEMS/NEMS" and encourage our colleagues to contribute their excellent work to this Special Issue. This Special Issue aims to highlight recent novel progresses in cutting-edge MEMS device technologies, including original research articles and topical reviews in the scope of materials, design and fabrication technologies, characterization methods, packaging and microsystem integration solutions. The topics of this Special Issue include, but are not limited to:

- Novel functional MEMS materials:
- Innovative MEMS mechanical and chemical sensors;
- Biological devices for wearable healthcare systems;
- Optical and quantum MEMS devices and systems;
- RF MEMS for telecommunication systems;
- MEMS devices for self-powered systems;
- Micro/nano fabrication process and integration;
- MEMS packaging and reliability issues.

Guest Editors

Dr. Nan Wang

Dr. Tao Wu

Dr. Jicong Zhao

Dr. Chen Liu

Deadline for manuscript submissions

closed (30 December 2022)



Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0 CiteScore 6.0 Indexed in PubMed



mdpi.com/si/109845

Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

mdpi.com/journal/ micromachines





an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed



About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

Prof. Dr. Ai-Qun Liu

Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank:

JCR - Q2 (Instruments and Instrumentation) / CiteScore - Q1 (Mechanical Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 17.2 days after submission; acceptance to publication is undertaken in 1.9 days (median values for papers published in this journal in the first half of 2025).

